Attracting Tomorrow



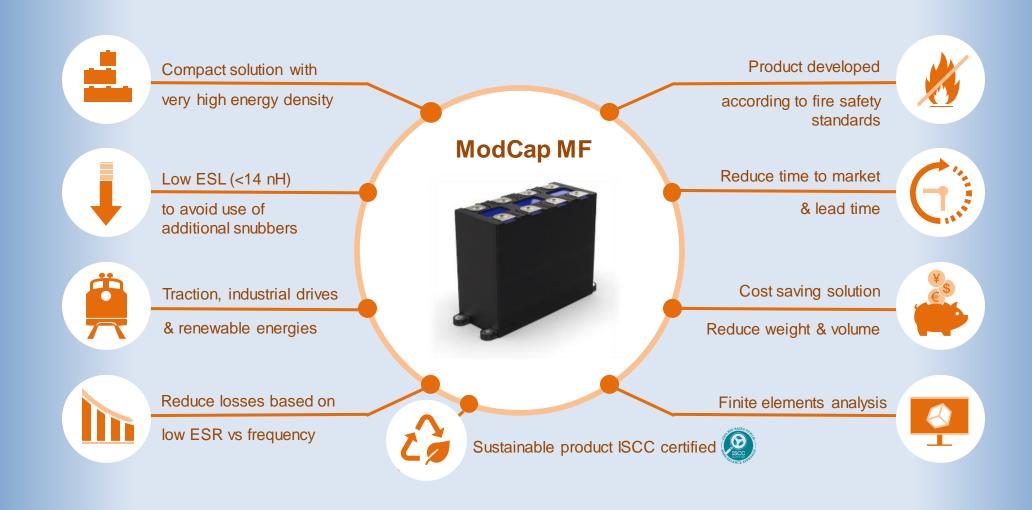
ModCap MF



Introducing the New Modular Standard Series Highlights









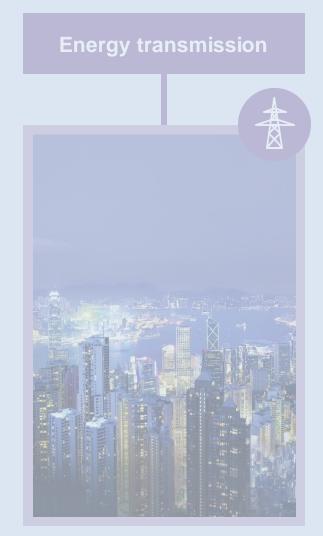
ModCap MF Series | B25645A*



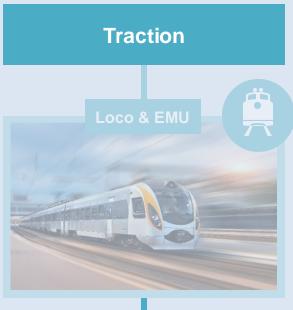
ModCap MF Series | B25645A* DC-Link Applications



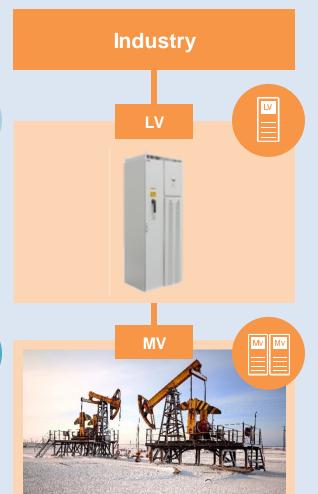


















ModCap HF (dry-modular-high frequency)

























Features

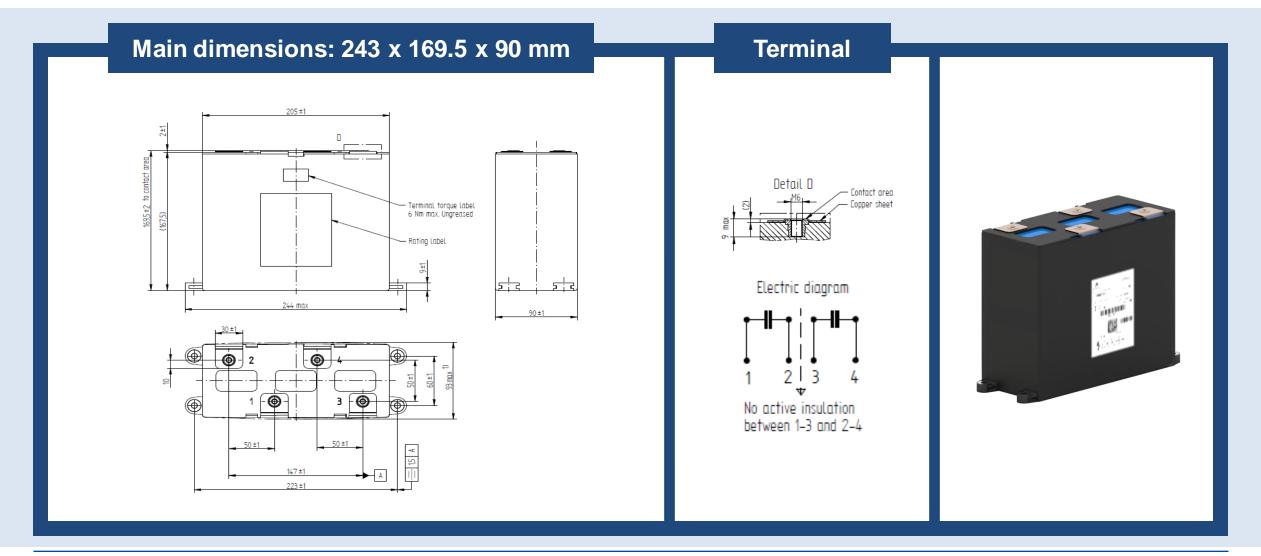
- 3900 µF
- Voltage range from 900 up to 2300 V DC
- Low ESL <14 nH
- Temperature range up to 90 °C hotspot
- IEC 61071, IEC 61881-1, EN 45545-2 HL3 R23 (fire and smoke) for the whole series
- UL recognized
- technology)
- Plastic case (open), Flat windings
- Sustainable product with 100% bio-based polypropylene film

Benefits

- Capacitance range from 350 up to High energy density, ultra compact solution
 - Modular concept for parallel connection
 - Snubber avoidance / low voltage overshoot
 - Lifetime up to 200,000 hours
 - Finite elements analysis available
 - Cost oriented solution
- Filled with polyurethane resin (dry Reduced time to market & lead time

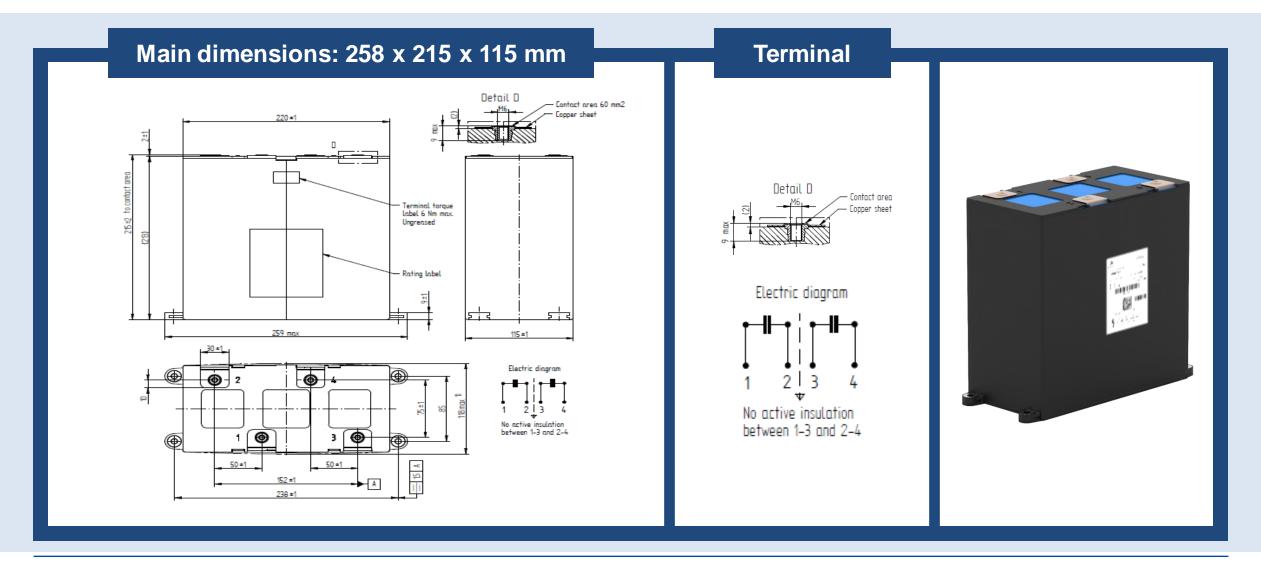






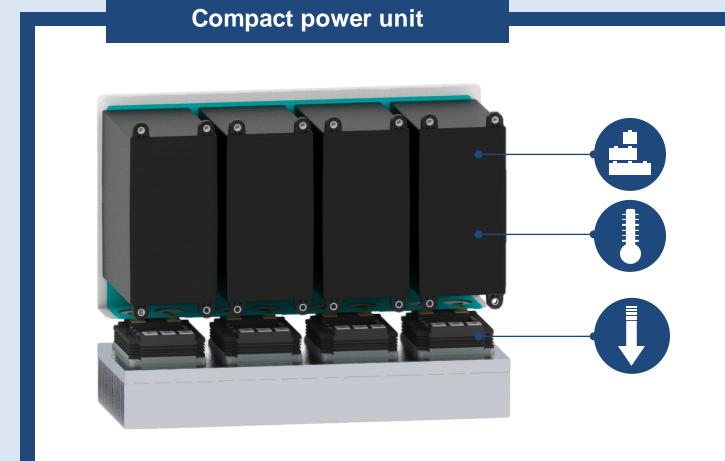
Construction B Simplified Drawing & 3-D





Highlights: Compactness, Low ESL & **Higher Operation Temperature**





- Capacitors can be mounted very close to the power modules to reduce loop inductance.
 - → Ultra compact solution
 - → Less investment on cooling
- Very short connection between capacitor and semiconductor
 - → Low ESL (<14 nH)
 - → Possible snubber capacitors avoidance





Electromagnetic: Modelling

Customer input

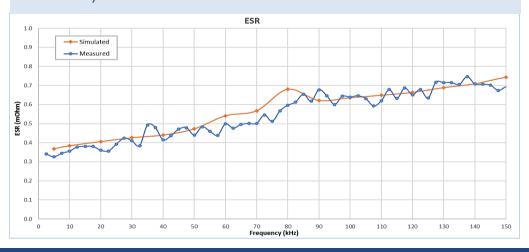
Current-frequency spectrum

TDK input

Capacitor design

Simulation

Capacitor electrical model: including ESL and ESR vs frequency Total losses and its internal distribution (must for accurate thermal simulation)

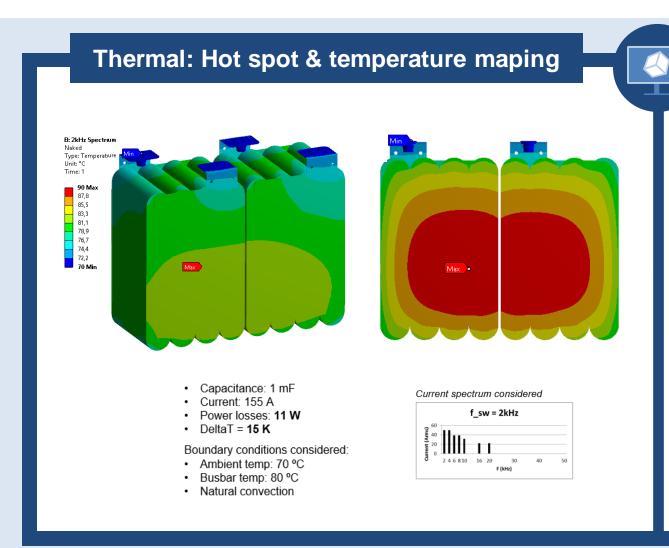


Customer benefits

- Electromagnetic model available for specific simulation according to current-frequency spectrum defined by the customer.
- Capacitor electrical model available in time and frequency domain
- Losses at defined current-frequency spectrum and its internal distribution
- Graphs with simulated ESR fully available for further thermal calculations by calculating losses all along the complete range of frequency



Thermal Behavior of Modular MF Series



Customer benefits

- Thermal model available for specific simulation according to spectrum and boundary conditions defined by the customer.
- Thermal simulations to be integrated as part of the type test report.
- Thermal simulations may reduce the complexity and time of technical approvals, no further specific thermal stability test on lab.
- Detailed temperature mapping allows customer to estimate in advance hot spot areas
- Thermal simulation to be done as per specific customer requirements (customized current spectrum and thermal boundary conditions)
- Heating transference from bus bar may be analyzed in advance

ModCap MF Ordering Code System



Nominal voltage (V)	Capacitance ±10% (μF)	Nominal current (A)	Surge current (kA)	Repetitive peak current (kA)	Dimensions (L x W x H, mm)	Con-struction	Part number
900	2075	200	225	5	205x90x170	Α	B25645A9218K003
	3900	155	250	5	220x115x215	В	B25645A9398K003
1000	1705	190	220	5	205x90x170	Α	B25645A1178K003
	3210	150	245	5	220x115x215	В	B25645A1328K003
1100	1330	180	215	5	243x169.5x90	Α	B25645A1138K003
	2525	140	240	5	258x215x115	В	B25645A1258K003
1250	1045	170	210	5	243x169.5x90	Α	B25645A1118K003
	1985	135	235	5	258x215x115	В	B25645A1198K003
1350	980	160	205	5	243x169.5x90	Α	B25645A1108K013
	1865	130	230	5	258x215x115	В	B25645A1188K003
1600	710	150	200	5	243x169.5x90	Α	B25645A1757K003
	1375	120	225	5	258x215x115	В	B25645A1138K013
1800	525	140	195	5	243x169.5x90	Α	B25645A1567K003
	1025	115	220	5	258x215x115	В	B25645A1108K003
2000	415	130	185	5	243x169.5x90	Α	B25645A2447K003
	820	110	210	5	258x215x115	В	B25645A2827K003
2300	335	120	175	5	243x169.5x90	Α	B25645A2367K003
	670	105	200	5	258x215x115	В	B25645A2677K003



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